

IWLPC 2012 - Another Smashing Success!

Ron Molnar, [AZ Tech Direct]

Interest in Wafer-Level Packaging (WLP) continues to expand as evidenced by the research presented by the early users and suppliers of this IC packaging technology at the most recent International Wafer-Level Packaging Conference (IWLPC) held November 5 – 8, 2012 in San Jose, CA. This premier event, co-organized by SMTA and Chip Scale Review, brought together 500 technologists from around the world to discuss recent advances in wafer level packaging, 3D integration, and MEMS design and assembly.

SMTA Administrator, JoAnn Stromberg noted, “The SMTA continues to welcome the opportunity to work with Chip Scale Review in presenting one of the industry’s strongest events dedicated to bringing together some of the semiconductor industry’s most respected authorities addressing all aspects of wafer-level, 3D, TSV, and MEMS device packaging. From the plenary sessions to the exhibit hall to the conference sessions, we were pleased with the support that was shown for this event as we approach our 10th IWLPC anniversary in 2013.”

This year’s event, led by General Chair, Andrew Strandjord of PacTech USA, and Technical Chair, Luu Nguyen of Texas Instruments, consisted of 29 technical presentations organized in three parallel tracks, two panel discussions, four half-day tutorials, two morning plenary sessions, and was capped off with an intriguing keynote dinner address.

MORE EXHIBITORS

Although the exhibit hall was expanded this year, it was completely “sold out” again with 52 exhibiting companies as compared to 44 last year. Steady supporters that have exhibited for the past five (5) years included: EV Group, Kyzen Corp., Pac Tech USA, Promex Industries, and TechSearch International.



Sandra Winkler & Karen Williams of New Venture Research



Paula Faria & Auie Sukys of Nanium S.A



Kim Newman of Chip Scale Review & Jim Rosson & Team of Dow Corning Electronic Solutions



Deborah Patterson & Debi Polo of Amkor Technology



Tim Olson & Garry Pycroft of Deca Technologies

Kim Newman, Publisher of Chip Scale Review, exclaimed, “As the co-organizer, promoting IWLPC is a year long effort resulting in a ‘sell-out’ from the keynote dinner to the exhibits. We



John McCarthy & Rick Trevino of Rudolph Technologies



Hitoshi Yokoyama & Team of Teramicros are pleased that 2012 brought in new faces and companies such as CAD Design Software, Compugraphics, Johnstech, KYEC USA, Sonoscan, and Zymet."

There were actually 20 new exhibitors this year. Other first-timers included Atotech, Deca Technologies, Disco, Dow Corning, Dow Electronic Materials, GDSI, IMT, Milestone, NuSil, Protavic, Rudolph Technologies, SEC, and SigmaTech.

MORE LEARNING

The four tutorial programs, taught by industry veterans, attracted 90 participants. As was the case last year, the two most popular tutorials once again were "Wafer Level Packaging" by Luu Nguyen, Ph.D., of Texas Instruments and "TSV and Other Key Enabling Technologies for 3D IC/Silicon Integration" by John H. Lau, Ph.D., of the Industrial Technology Research Institute (ITRI).

MORE SHARING

The morning plenary sessions offered two perspectives on how to attain the many benefits of wafer level packaging. Dr. Nicolas Sillon of CEA-Leti described the 2.5D integration approach using silicon interposers in his presentation titled, "Silicon Interposer:



Keynote Address & Dinner



Dr. Nicolas Sillon of CEA-Leti

Much More than a 'Piece of Silicon'." Dr. Paul Marchal of IMEC described the challenges and benefits of WLP using a complete 3D approach in his presentation titled, "3D Integration – A Corner Technology for Heterogeneous Integration."

The 29 technical talks described many new materials, equipment capabilities, and unique processes developed specifically for the manufacturing of wafer level and MEMS-based IC

products to attain performance goals associated with smaller footprint and shorter interconnects.

MORE NETWORKING

The sold-out, keynote dinner featured a thought-provoking address, titled "A Trojan Chip in Your Smartphone? It's Coming" by John Ellis, a semiconductor industry veteran turned best-selling author of *Dormant Curse*. He introduced the audience to some of the fictional characters in his novel and warned of some of the dangers that could be exploited in our mobile wireless society.

MORE CONTRIBUTORS

The success of industry events, like IWLPC, depends on contributions from many volunteers and organizations. In addition to 52 corporate exhibitors, there were 10 corporate sponsors this year led by the three Platinum Level contributors:

Amkor Technology, Invensas, and STATSChipPAC. Kim Newman acknowledged, "We couldn't do it without the support of these various sponsors!"

ATTEND IWLPC 2013

Planning is already underway for the 10th Anniversary of IWLPC in Fall, 2013. Check the website, www.iwlpc.com, for more details as they become available.